



Vincotech

10-EY232PB006ME01-PN98F08T

datasheet

flowDUAL E2 SiC

2300 V / 6 mΩ

Topology features

- Temperature sensor
- Half Bridge

Component features

- Fast intrinsic diode with low reverse recovery
- High blocking voltage with low on-resistance
- High speed switching with low capacitance

Housing features

- Base isolation: AlN
- Convex shaped substrate for superior thermal contact
- Compact housing
- CTI600 housing material
- Thermo-mechanical push-and-pull force relief
- Press-fit pin
- Reliable cold welding connection

Target applications

- Charging Stations
- Energy Storage Systems
- General
- Industrial Drives
- Power Supply
- UPS
- Welding & Cutting

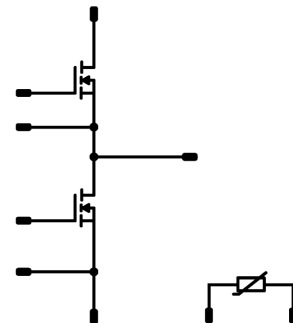
Types

- 10-EY232PB006ME01-PN98F08T

flow E2 12 mm housing



Schematic





Vincotech

10-EY232PB006ME01-PN98F08T
datasheet

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Inverter Switch				
Drain-source voltage	V_{DS}		2300	V
Drain current (DC current)	I_D	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	184	A
Peak drain current	I_{DM}	t_p limited by T_{jmax}	830	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	568	W
Gate-source voltage	V_{GS}	static	-4 / 15	V
		dynamic	-8 / 19	V
Maximum Junction Temperature	T_{jmax}		175	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6800	V
Creepage distance			>12,7	mm
Clearance			9,05	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Inverter Switch

Static

Drain-source on-state resistance	$r_{DS(on)}$		15		345	25 125 150		6,74 13,4 15,8	7,8 ⁽¹⁾	mΩ
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$			0,095	25	1,8	2,5	3,6	V
Gate to Source Leakage Current	I_{GSS}		15	0		25		50	500	nA
Zero Gate Voltage Drain Current	I_{DSS}		0	2300		25		5	50	μA
Internal gate resistance	r_g							1,2		Ω
Gate charge	Q_g		-4/15	1500	345	25		735		nC
Short-circuit input capacitance	C_{iss}	$f = 100$ kHz	0	1500	0	25		30000		pF
Short-circuit output capacitance	C_{oss}							510		
Reverse transfer capacitance	C_{rss}							50		
Diode forward voltage	V_{SD}		0		175	25		5,5		V

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 5,2$ W/mK (PTM)						0,17		K/W
--	---------------	---------------------------------------	--	--	--	--	--	------	--	-----



Vincotech

10-EY232PB006ME01-PN98F08T

datasheet

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit				
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max					
Dynamic														
Turn-on delay time	$t_{d(on)}$	$R_{gon} = 0,5 \Omega$ $R_{goff} = 0,5 \Omega$	-4/15	1200	345	25		33,91		ns				
						125		32,07						
						150		31,62						
Rise time	t_r									25		17,33		ns
										125		16,48		
										150		16,14		
Turn-off delay time	$t_{d(off)}$									25		136,75		ns
										125		153,32		
										150		157,07		
Fall time	t_f									25		16,86		ns
										125		17,35		
										150		17,72		
Turn-on energy (per pulse)	E_{on}	$Q_{rFWD}=2,48 \mu C$ $Q_{rFWD}=6,12 \mu C$ $Q_{rFWD}=9,66 \mu C$				25		6,34		mWs				
						125		6,8						
						150		7,58						
Turn-off energy (per pulse)	E_{off}					25		8,99		mWs				
						125		9,87						
						150		10,22						
Peak recovery current	I_{RRM}	$di/dt=25920 A/\mu s$ $di/dt=29631 A/\mu s$ $di/dt=30690 A/\mu s$				25		202,38		A				
							125		273,03					
							150		349,88					
Reverse recovery time	t_{rr}						25		22,31		ns			
							125		38,46					
							150		47,49					
Recovered charge	Q_r						25		2,48		μC			
							125		6,12					
							150		9,66					
Reverse recovered energy	E_{rec}						25		1,79		mWs			
							125		5,49					
							150		9,03					
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25		22304,21		A/ μs				
						125		14290,6						
						150		18330,95						



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Thermistor

Static

Rated resistance	R					25		5		k Ω
Deviation of R100	$\Delta_{R/R}$	$R_{100} = 499 \Omega$				100	3,2		3,3	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,3		mW/K
B-value	$B_{(25/50)}$	Tol. $\pm 1 \%$						3380		K
Vincotech Thermistor Reference									V	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.



Vincotech

Inverter Switch Characteristics

figure 1. MOSFET

Typical output characteristics

$$I_D = f(V_{DS})$$

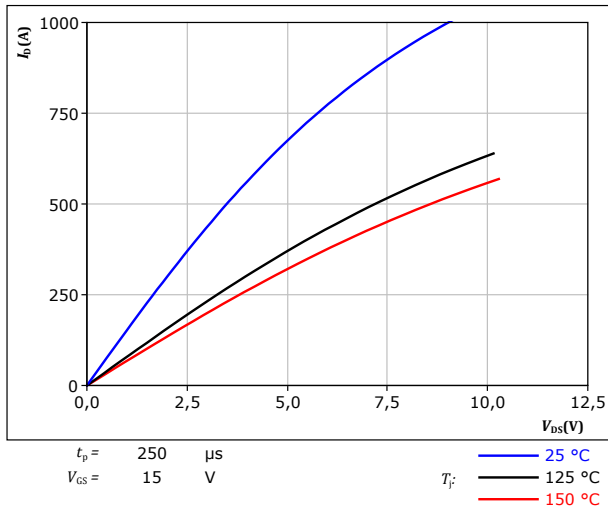


figure 2. MOSFET

Typical output characteristics

$$I_D = f(V_{DS})$$

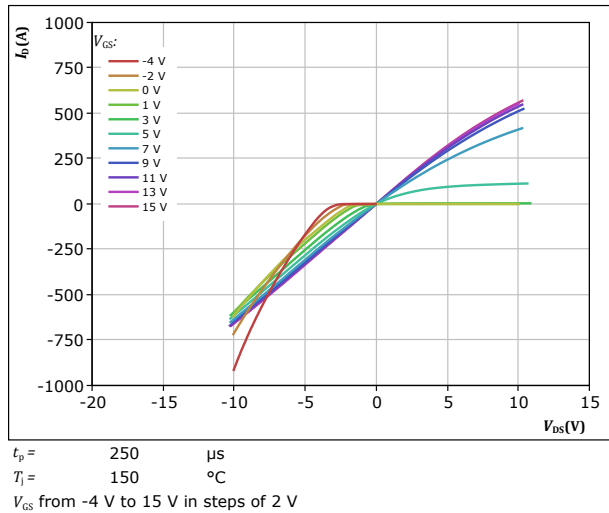


figure 3. MOSFET

Typical transfer characteristics

$$I_D = f(V_{GS})$$

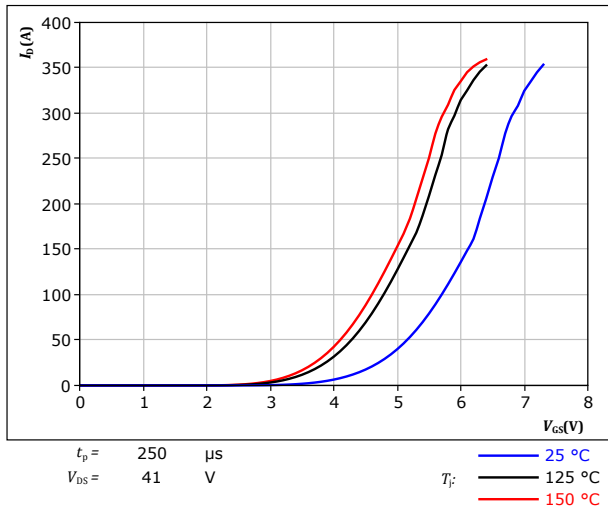
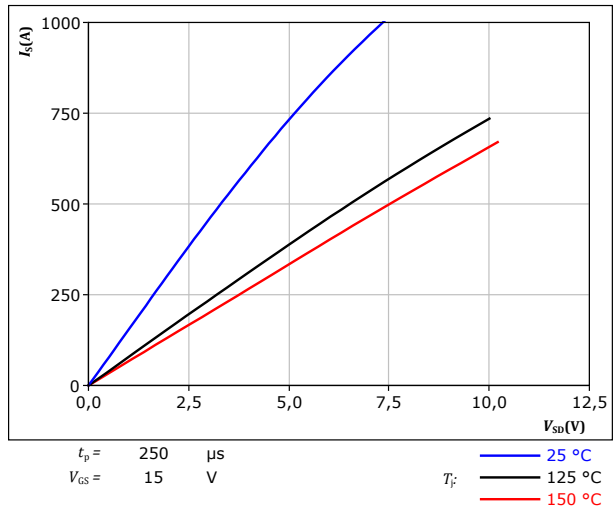


figure 4. MOSFET

Typical reverse drain current characteristics

$$I_{SD} = f(V_{SD})$$





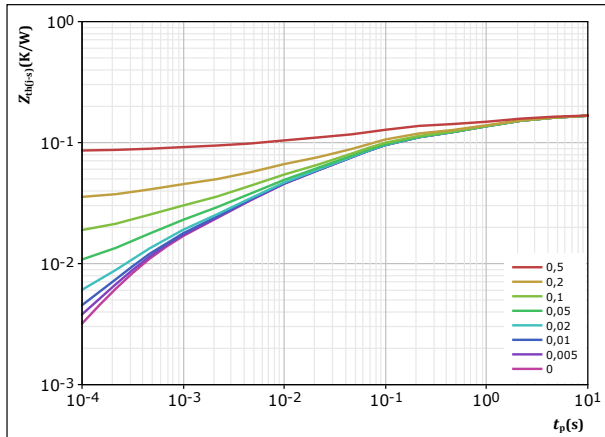
Vincotech

Inverter Switch Characteristics

figure 5. MOSFET

Transient thermal impedance as a function of pulse width

$$Z_{th(j-a)} = f(t_p)$$



$$D = t_p / T$$

$$R_{th(j-a)} = 0,167 \text{ K/W}$$

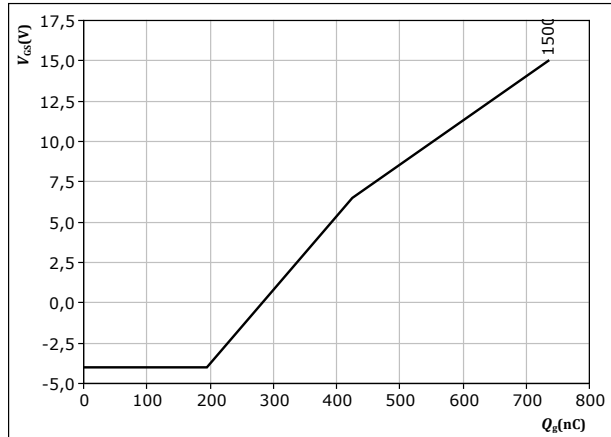
MOSFET thermal model values

R (K/W)	τ (s)
2,08E-02	5,73E+00
4,77E-02	9,28E-01
6,27E-02	5,96E-02
2,72E-02	5,03E-03
1,20E-02	4,20E-04

figure 6. MOSFET

Gate voltage vs gate charge

$$V_{GS} = f(Q_g)$$



$$I_D = 250 \text{ A}$$

$$T_j = 25 \text{ }^{\circ}\text{C}$$



Vincotech

10-EY232PB006ME01-PN98F08T
datasheet

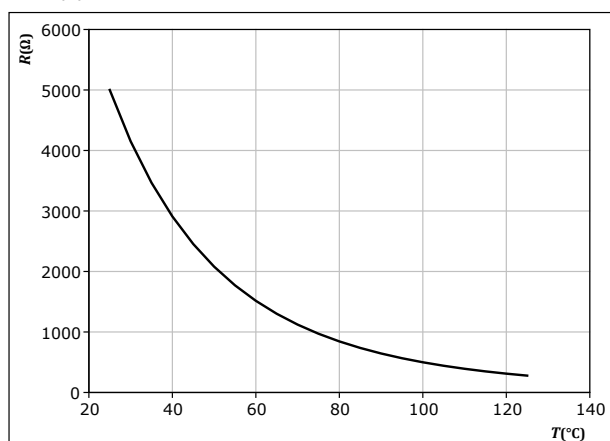
Thermistor Characteristics

figure 7.

Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$





Vincotech

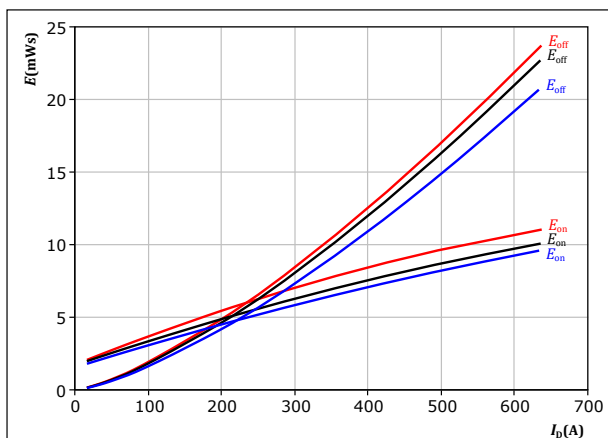
Inverter Switching Characteristics

figure 8.

MOSFET

Typical switching energy losses as a function of drain current

$$E = f(I_D)$$



With an inductive load at

$V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $R_{gon} = 0,5$ Ω
 $R_{goff} = 0,5$ Ω

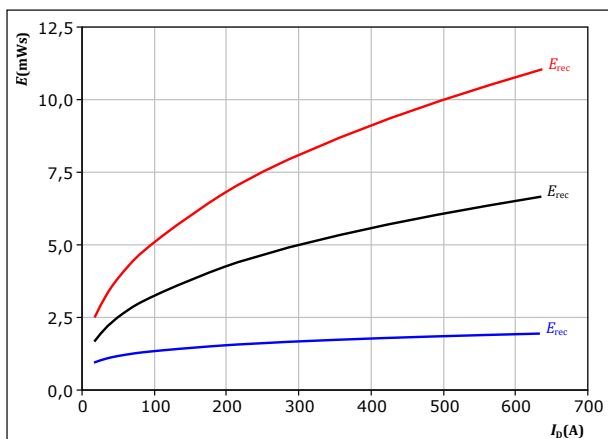
T_j : 25 °C
125 °C
150 °C

figure 10.

MOSFET

Typical reverse recovered energy loss as a function of drain current

$$E_{rec} = f(I_D)$$



With an inductive load at

$V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $R_{gon} = 0,5$ Ω

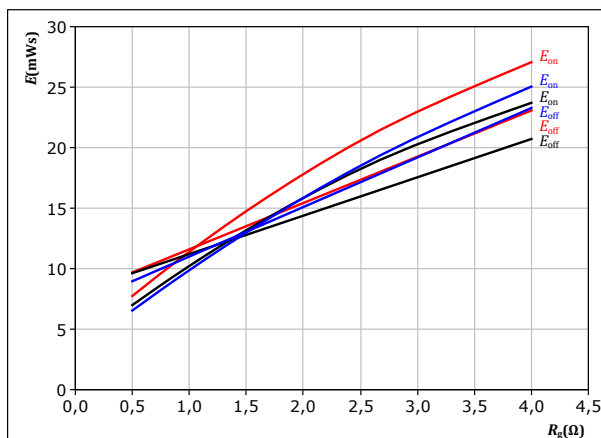
T_j : 25 °C
125 °C
150 °C

figure 9.

MOSFET

Typical switching energy losses as a function of MOSFET turn on gate resistor

$$E = f(R_g)$$



With an inductive load at

$V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $I_D = 345$ A

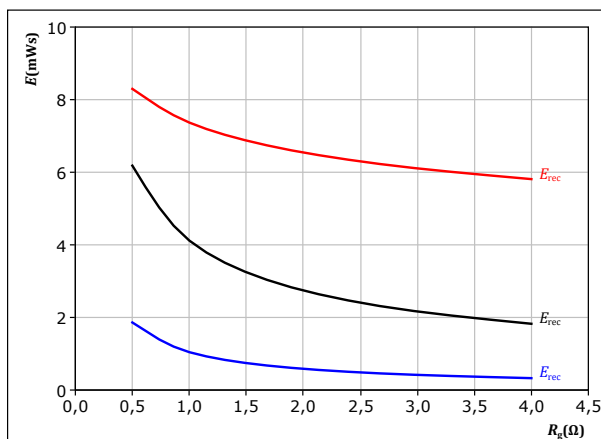
T_j : 25 °C
125 °C
150 °C

figure 11.

MOSFET

Typical reverse recovered energy loss as a function of MOSFET turn on gate resistor

$$E_{rec} = f(R_g)$$



With an inductive load at

$V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $I_D = 345$ A

T_j : 25 °C
125 °C
150 °C



Vincotech

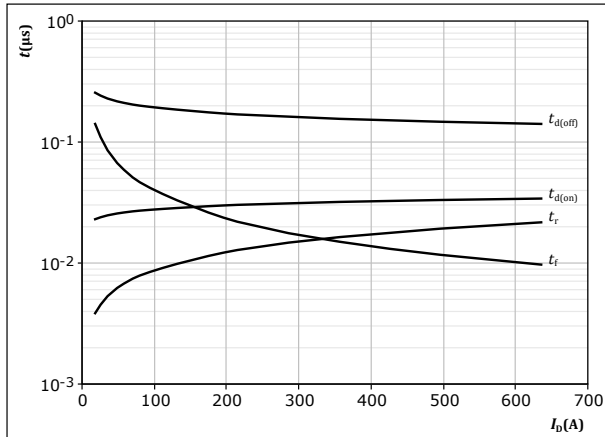
10-EY232PB006ME01-PN98F08T datasheet

Inverter Switching Characteristics

figure 12.

MOSFET

Typical switching times as a function of drain current
 $t = f(I_D)$



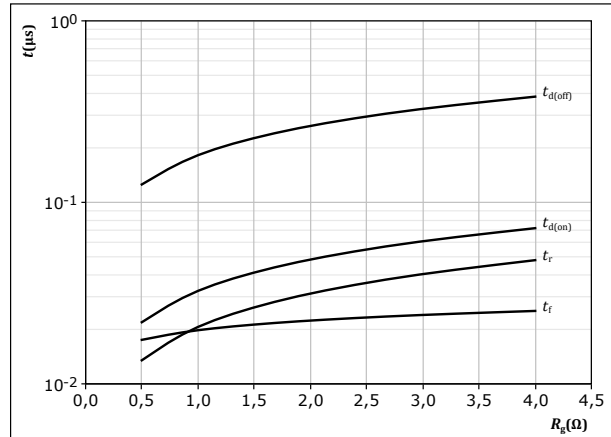
With an inductive load at

$T_j = 150$ °C
 $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $R_{gon} = 0,5$ Ω
 $R_{goff} = 0,5$ Ω

figure 13.

MOSFET

Typical switching times as a function of MOSFET turn on gate resistor
 $t = f(R_g)$



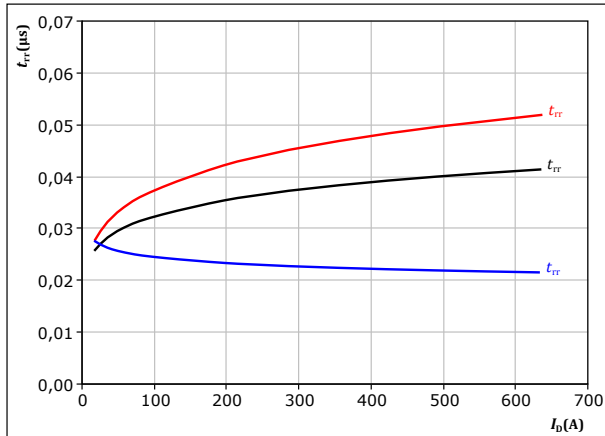
With an inductive load at

$T_j = 150$ °C
 $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $I_D = 345$ A

figure 14.

MOSFET

Typical reverse recovery time as a function of drain current
 $t_{rr} = f(I_D)$



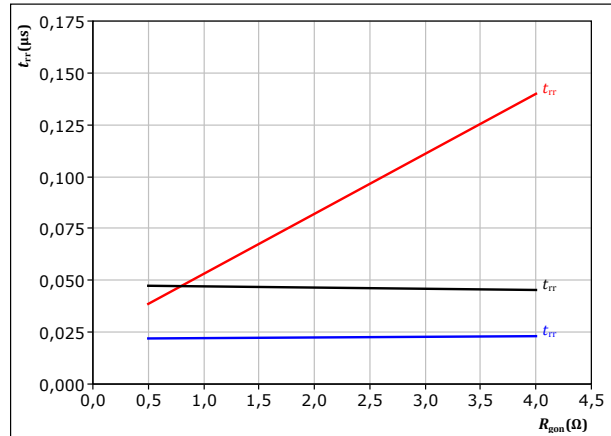
At $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $R_{gon} = 0,5$ Ω

T_j : — 25 °C
— 125 °C
— 150 °C

figure 15.

MOSFET

Typical reverse recovery time as a function of MOSFET turn on gate resistor
 $t_{rr} = f(R_{gon})$



At $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $I_D = 345$ A

T_j : — 25 °C
— 125 °C
— 150 °C



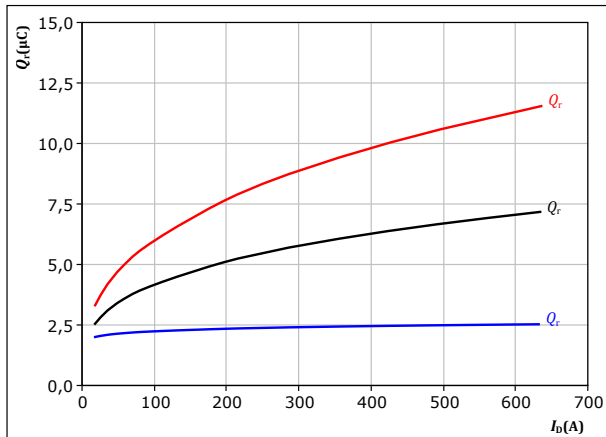
Vincotech

Inverter Switching Characteristics

figure 16. MOSFET

Typical recovered charge as a function of drain current

$$Q_r = f(I_D)$$

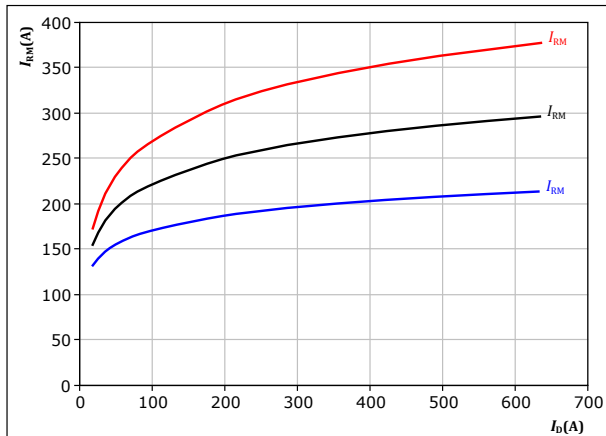


At $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $R_{gon} = 0,5$ Ω
 T_j : 25 °C
125 °C
150 °C

figure 18. MOSFET

Typical peak reverse recovery current as a function of drain current

$$I_{RM} = f(I_D)$$

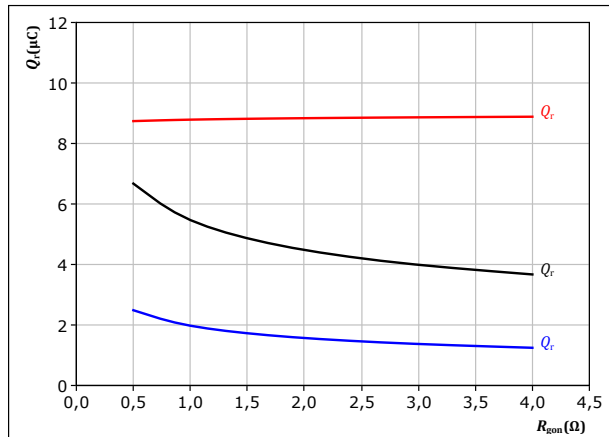


At $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $R_{gon} = 0,5$ Ω
 T_j : 25 °C
125 °C
150 °C

figure 17. MOSFET

Typical recovered charge as a function of MOSFET turn on gate resistor

$$Q_r = f(R_{gon})$$

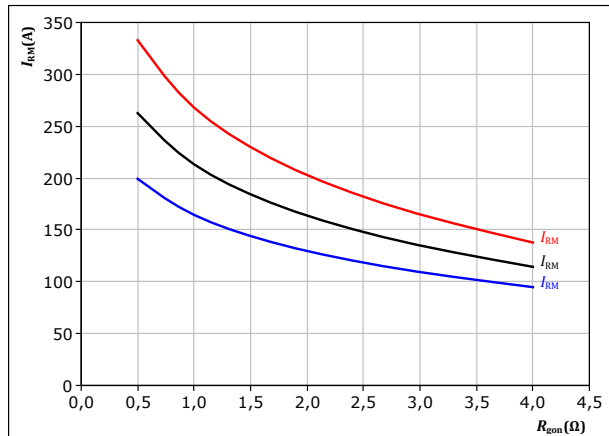


At $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $I_D = 345$ A
 T_j : 25 °C
125 °C
150 °C

figure 19. MOSFET

Typical peak reverse recovery current as a function of MOSFET turn on gate resistor

$$I_{RM} = f(R_{gon})$$



At $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $I_D = 345$ A
 T_j : 25 °C
125 °C
150 °C



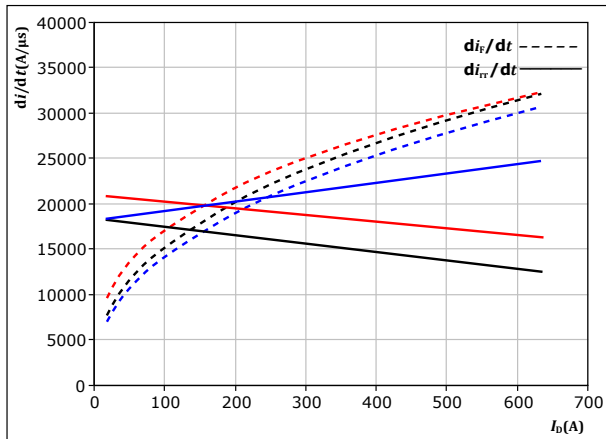
Vincotech

10-EY232PB006ME01-PN98F08T
datasheet

Inverter Switching Characteristics

figure 20. MOSFET

Typical rate of fall of forward and reverse recovery current as a function of drain current
 $di_f/dt, di_r/dt = f(I_D)$

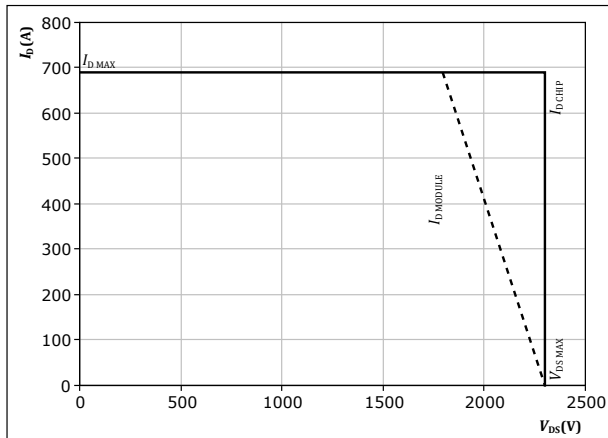


At $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $R_{gon} = 0,5$ Ω
 $T_j = 25$ °C
 125 °C
 150 °C

figure 22. MOSFET

Reverse bias safe operating area

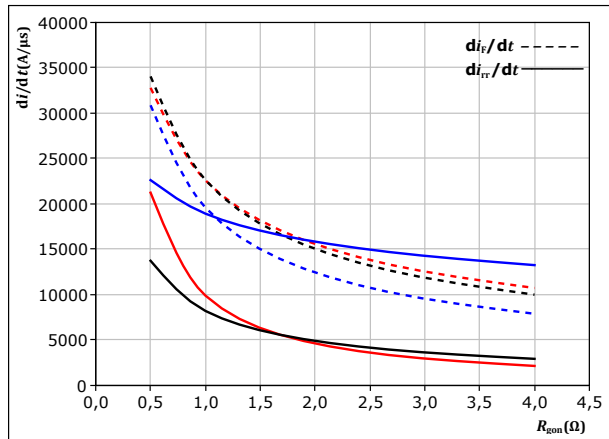
$I_D = f(V_{DS})$



At $T_j = 150$ °C
 $R_{gon} = 0,5$ Ω
 $R_{goff} = 0,5$ Ω

figure 21. MOSFET

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$



At $V_{DS} = 1200$ V
 $V_{GS} = -4/15$ V
 $I_D = 345$ A
 $T_j = 25$ °C
 125 °C
 150 °C



Vincotech

10-EY232PB006ME01-PN98F08T
datasheet

Inverter Switching Definitions

figure 23. MOSFET

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

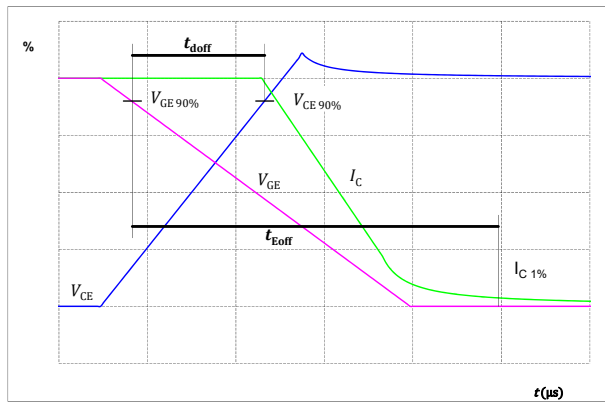


figure 24. MOSFET

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

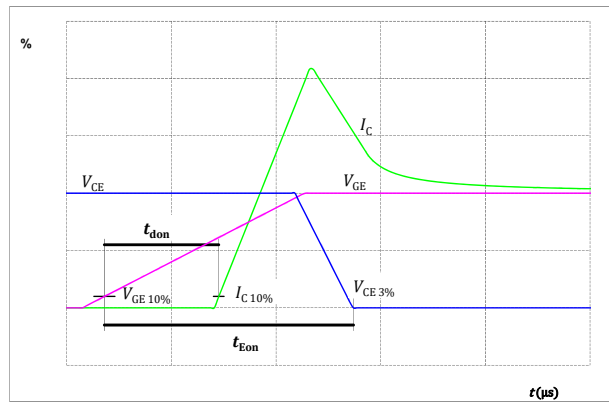


figure 25. MOSFET

Turn-off Switching Waveforms & definition of t_f

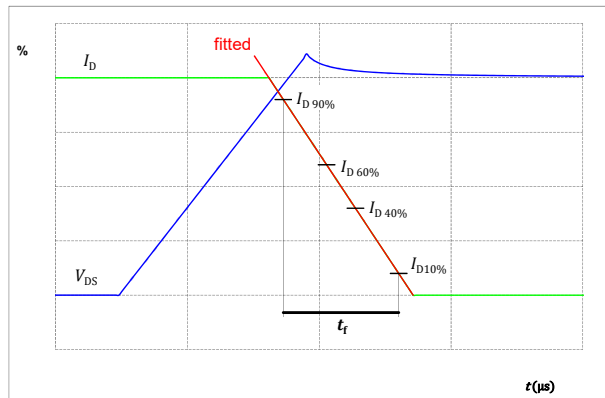
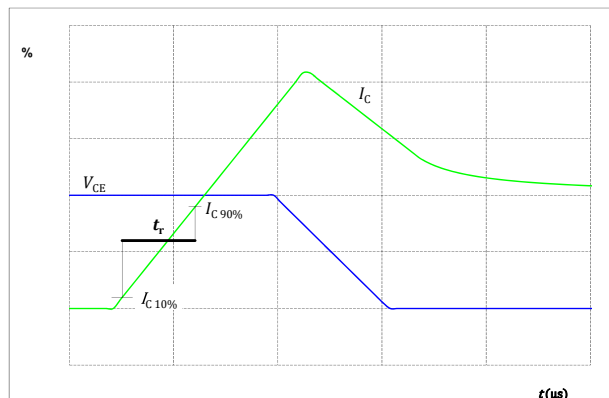


figure 26. MOSFET

Turn-on Switching Waveforms & definition of t_r





Vincotech

Inverter Switching Definitions

figure 27. FWD

Turn-off Switching Waveforms & definition of t_{tr}

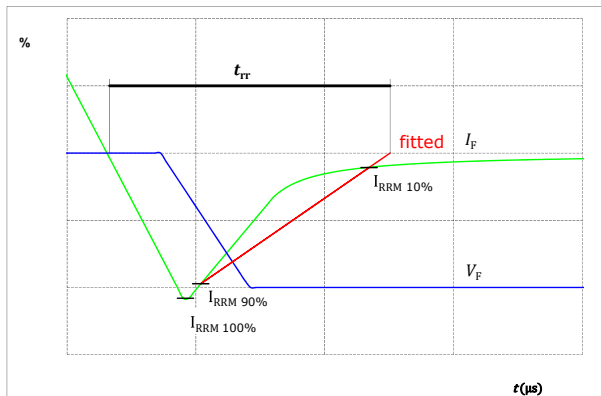


figure 28. FWD

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)

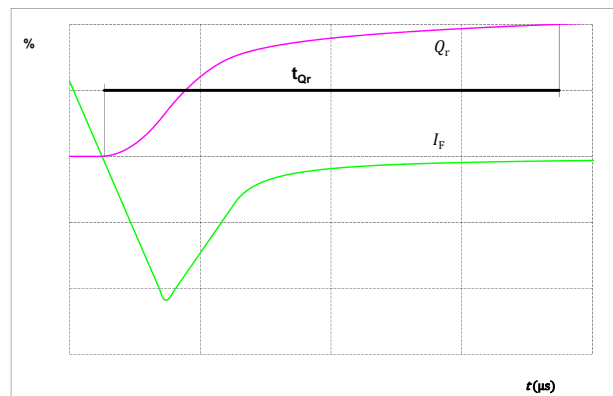
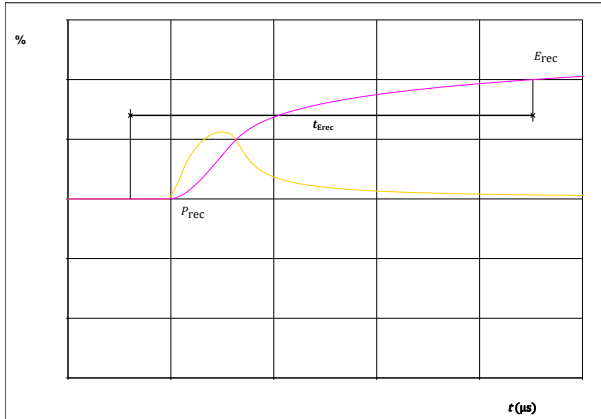


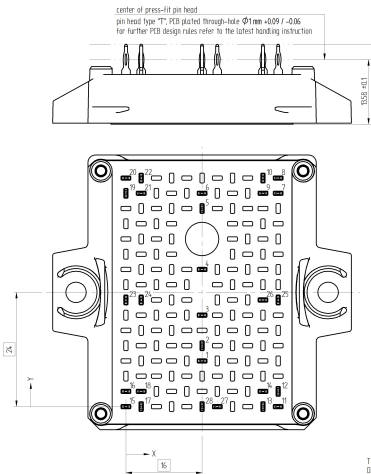
figure 29. FWD

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})





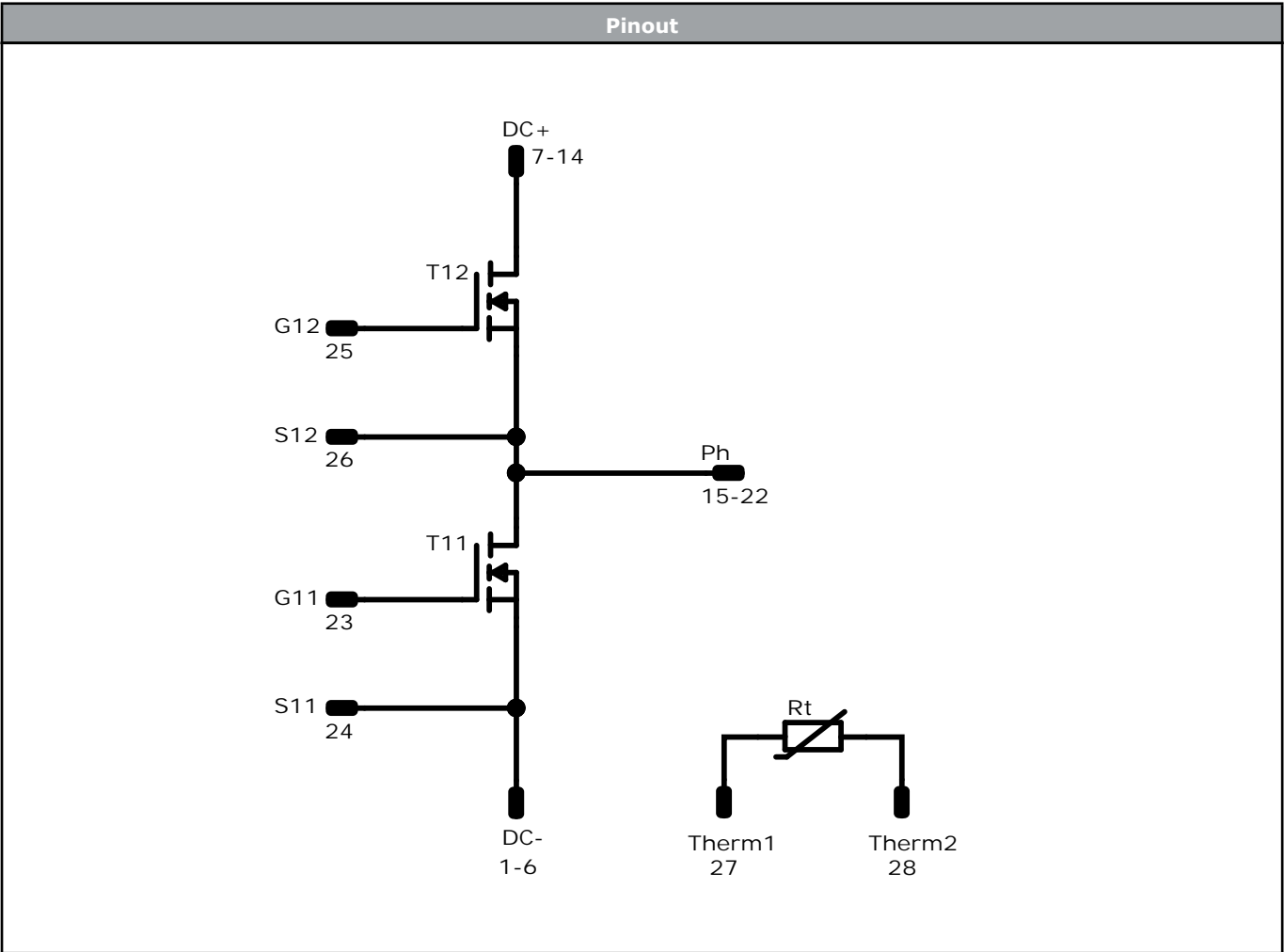
datasheet

Pin table [mm]				Outline	
Pin	X	Y	Function	 <p>center of press-fit pin head pin head type "T": PCB plated through-hole $\Phi 1\text{mm} \pm 0.09 / \pm 0.06$ for further PCB design rules refer to the latest handling instruction</p> <p>Tolerance of positions: $\pm 0.1\text{mm}$ at the end of pins Dimension of coordinate axis is only offset without tolerance</p>	
1	16	9,6	DC-		
2	16	12,8	DC-		
3	16	19,2	DC-		
4	16	28,8	DC-		
5	16	41,6	DC-		
6	16	44,8	DC-		
7	32	44,8	DC+		
8	32	48	DC+		
9	28,8	44,8	DC+		
10	28,8	48	DC+		
11	32	0	DC+		
12	32	3,2	DC+		
13	28,8	0	DC+		
14	28,8	3,2	DC+		
15	0	0	Ph		
16	0	3,2	Ph		
17	3,2	0	Ph		
18	3,2	3,2	Ph		
19	0	44,8	Ph		
20	0	48	Ph		
21	3,2	44,8	Ph		
22	3,2	48	Ph		
23	0	22,4	G11		
24	3,2	22,4	S11		
25	32	22,4	G12		
26	28,8	22,4	S12		
27	19,2	0	Therm1		
28	16	0	Therm2		



Vincotech

10-EY232PB006ME01-PN98F08T
datasheet




Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12	MOSFET	2300 V	6 mΩ	Inverter Switch	
Rt	Thermistor			Thermistor	



Vincotech

10-EY232PB006ME01-PN98F08T
datasheet

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample
Handling instruction				
Handling instructions for <i>flow</i> E2 packages see vincotech.com website.				
Package data				
Package data for <i>flow</i> E2 packages see vincotech.com website.				
Vincotech thermistor reference				
See Vincotech thermistor reference table at vincotech.com website.				
UL recognition and file number				
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}=175^{\circ}\text{C}$ and up to 4000VAC/1min isolation voltage. For more information see vincotech.com website.				

Document No.:	Date:	Modification:	Pages
10-EY232PB006ME01-PN98F08T-D1-14	28 May. 2026	Initial Release	

DISCLAIMER

The information, specifications, procedures, methods and recommendations herein (together "information") are presented by Vincotech to reader in good faith, are believed to be accurate and reliable, but may well be incomplete and/or not applicable to all conditions or situations that may exist or occur. Vincotech reserves the right to make any changes without further notice to any products to improve reliability, function or design. No representation, guarantee or warranty is made to reader as to the accuracy, reliability or completeness of said information or that the application or use of any of the same will avoid hazards, accidents, losses, damages or injury of any kind to persons or property or that the same will not infringe third parties rights or give desired results. It is reader's sole responsibility to test and determine the suitability of the information and the product for reader's intended use.

LIFE SUPPORT POLICY

Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.